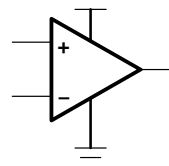


TLV271, TLV272, TLV274 FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

- Rail-To-Rail Output
- Wide Bandwidth . . . 3 MHz
- High Slew Rate . . . 2.4 V/ μ s
- Supply Voltage Range . . . 2.7 V to 16 V
- Supply Current . . . 550 μ A/Channel
- Input Noise Voltage . . . 39 nV/ $\sqrt{\text{Hz}}$
- Input Bias Current . . . 1 pA
- Specified Temperature Range
 - 0°C to 70°C . . . Commercial Grade
 - 40°C to 125°C . . . Industrial Grade
- Ultrasmall Packaging
 - 5 Pin SOT-23 (TLV271)
 - 8 Pin MSOP (TLV272)
- Ideal Upgrade for TLC27x Family

Operational Amplifier



description

The TLV27x takes the minimum operating supply voltage down to 2.7 V over the extended industrial temperature range while adding the rail-to-rail output swing feature. This makes it an ideal alternative to the TLC27x family for applications where rail-to-rail output swings are essential. The TLV27x also provides 3-MHz bandwidth from only 550 μ A.

Like the TLC27x, the TLV27x is fully specified for 5-V and $\pm$ 5-V supplies. The maximum recommended supply voltage is 16 V, which allows the devices to be operated from a variety of rechargeable cells ($\pm$ 8 V supplies down to $\pm$ 1.35 V).

The CMOS inputs enable use in high-impedance sensor interfaces, with the lower voltage operation making an attractive alternative for the TLC27x in battery-powered applications.

All members are available in PDIP and SOIC with the singles in the small SOT-23 package, duals in the MSOP, and quads in the TSSOP package.

The 2.7-V operation makes it compatible with Li-Ion powered systems and the operating supply voltage range of many micropower microcontrollers available today including TI's MSP430.

SELECTION OF SIGNAL AMPLIFIER PRODUCTS†

DEVICE	V _{DD} (V)	V _{IO} (μ V)	I _q /Ch (μ A)	I _B (pA)	GBW (MHz)	SR (V/ μ s)	SHUTDOWN	RAIL-TO-RAIL	SINGLES/DUALS/QUADS
TLV27x	2.7–16	500	550	1	3	2.4	—	O	S/D/Q
TLC27x	3–16	1100	675	1	1.7	3.6	—	—	S/D/Q
TLV237x	2.7–16	500	550	1	3	2.4	Yes	I/O	S/D/Q
TLC227x	4–16	300	1100	1	2.2	3.6	—	O	D/Q
TLV246x	2.7–6	150	550	1300	6.4	1.6	Yes	I/O	S/D/Q
TLV247x	2.7–6	250	600	2	2.8	1.5	Yes	I/O	S/D/Q
TLV244x	2.7–10	300	725	1	1.8	1.4	—	O	D/Q

† Typical values measured at 5 V, 25°C



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2002, Texas Instruments Incorporated

TLV271, TLV272, TLV274

FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

FAMILY PACKAGE TABLE

DEVICE	NUMBER OF CHANNELS	PACKAGE TYPES					SHUTDOWN	UNIVERSAL EVM BOARD
		PDIP	SOIC	SOT-23	TSSOP	MSOP		
TLV271	1	8	8	5	—	—	—	Refer to the EVM Selection Guide (Lit# SLOU060)
TLV272	2	8	8	—	—	8	—	
TLV274	4	14	14	—	14	—	—	

TLV271 AVAILABLE OPTIONS

T _A	V _{IO} MAX AT 25°C	PACKAGED DEVICES			
		SMALL OUTLINE (D) [†]	SOT-23		PLASTIC DIP (P)
			(DBV) [‡]	SYMBOL	
0°C to 70°C	5 mV	TLV271CD	TLV271CDBV	VBHC	—
–40°C to 125°C		TLV271ID	TLV271IDBV	VBHI	TLV271IP

[†] This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV271IDR).

[‡] This package is only available taped and reeled. For standard quantities (3,000 pieces per reel), add an R suffix (e.g., TLV270IDBVR). For smaller quantities (250 pieces per mini-reel), add a T suffix to the part number (e.g., TLV270IDBVT).

TLV272 AVAILABLE OPTIONS

T _A	V _{IO} MAX AT 25°C	PACKAGED DEVICES			
		SMALL OUTLINE (D) [§]	MSOP		PLASTIC DIP (P)
			(DGK) [§]	SYMBOL	
0°C to 70°C	5 mV	TLV272CD	TLV272CDGK	AVF	—
–40°C to 125°C		TLV272ID	TLV272IDGK	AVG	TLV272IP

[§] This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV272IDR).

TLV274 AVAILABLE OPTIONS

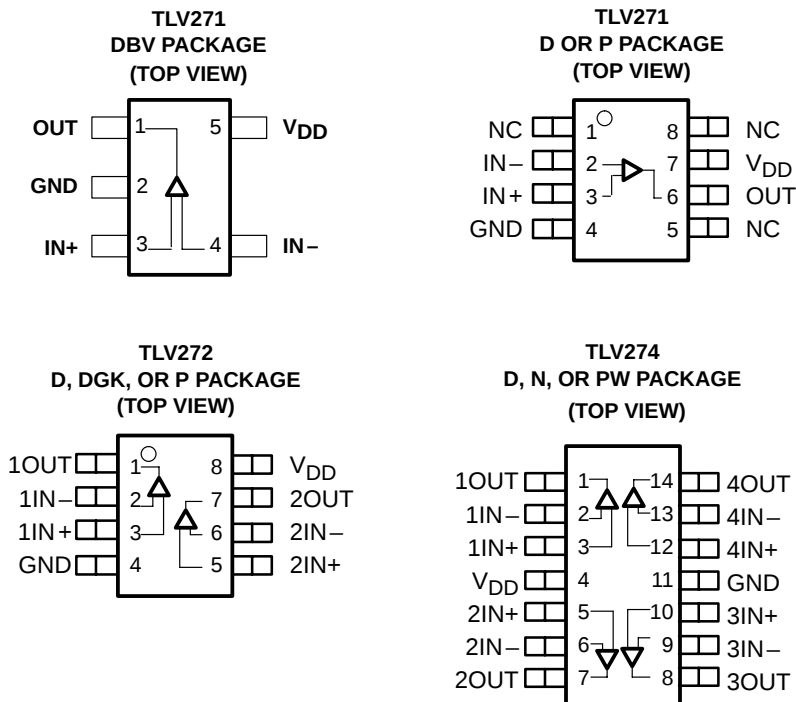
T _A	V _{IO} MAX AT 25°C	PACKAGED DEVICES		
		SMALL OUTLINE (D) [¶]	PLASTIC DIP (N)	TSSOP (PW) [¶]
0°C to 70°C	5 mV	TLV274CD	—	TLV274CPW
–40°C to 125°C		TLV274ID	TLV274IN	TLV274IPW

[¶] This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV274IDR).

TLV271, TLV272, TLV274 FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

TLV27x PACKAGE PINOUTS



NC – No internal connection

TLV271, TLV272, TLV274

FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{DD} (see Note 1)	16.5 V
Differential input voltage, V_{ID}	$\pm V_{DD}$
Input voltage range, V_I (see Note 1)	-0.2 V to $V_{DD} + 0.2$ V
Input current range, I_I	± 10 mA
Output current range, I_O	± 100 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A : C suffix	0°C to 70°C
I suffix	-40°C to 125°C
Maximum junction temperature, T_J	150°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to GND.

DISSIPATION RATING TABLE

PACKAGE	θ_{JC} (°C/W)	θ_{JA} (°C/W)	$T_A \leq 25^\circ\text{C}$ POWER RATING	$T_A = 25^\circ\text{C}$ POWER RATING
D (8)	38.3	176	710 mW	396 mW
D (14)	26.9	122.3	1022 mW	531 mW
D (16)	25.7	114.7	1090 mW	567 mW
DBV (5)	55	324.1	385 mW	201 mW
DBV (6)	55	294.3	425 mW	221 mW
DGK (8)	54.23	259.96	481 mW	250 mW
DGS (10)	54.1	257.71	485 mW	252 mW
N (14, 16)	32	78	1600 mW	833 mW
P (8)	41	104	1200 mW	625 mW
PW (14)	29.3	173.6	720 mW	374 mW
PW (16)	28.7	161.4	774 mW	403 mW

recommended operating conditions

		MIN	MAX	UNIT
Supply voltage, V_{DD}	Single supply	2.7	16	V
	Split supply	± 1.35	± 8	
Common-mode input voltage range, V_{ICR}		0	$V_{DD} - 1.35$	V
Operating free-air temperature, T_A	C-suffix	0	70	°C
	I-suffix	-40	125	

TLV271, TLV272, TLV274
FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT
OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

electrical characteristics at specified free-air temperature, $V_{DD} = 2.7\text{ V}$, 5 V , and $\pm 5\text{ V}$ (unless otherwise noted)

dc performance

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
V_{IO} Input offset voltage	$V_{IC} = V_{DD}/2$, $R_L = 150\ \Omega$, $V_O = V_{DD}/2$, $R_S = 50\ \Omega$	25°C		0.5	5	mV
		Full range			7	
α_{VIO} Offset voltage drift		25°C		2		$\mu\text{V}/^\circ\text{C}$
CMRR Common-mode rejection ratio	$V_{IC} = 0\text{ to }V_{DD}-1.35\text{ V}$, $R_S = 50\ \Omega$	$V_{DD} = 2.7\text{ V}$	25°C	58	70	dB
			Full range	55		
	$V_{IC} = 0\text{ to }V_{DD}-1.35\text{ V}$, $R_S = 50\ \Omega$	$V_{DD} = 5\text{ V}$	25°C	69	85	
			Full range	64		
	$V_{IC} = -5\text{ to }V_{DD}-1.35\text{ V}$, $R_S = 50\ \Omega$	$V_{DD} = \pm 5\text{ V}$	25°C	69	85	
			Full range	66		
A_{VD} Large-signal differential voltage amplification	$V_{O(PP)} = V_{DD}/2$, $R_L = 10\text{ k}\Omega$	$V_{DD} = 2.7\text{ V}$	25°C	97	106	dB
			Full range	76		
		$V_{DD} = 5\text{ V}$	25°C	100	110	
			Full range	86		
		$V_{DD} = \pm 5\text{ V}$	25°C	100	115	
			Full range	90		

† Full range is 0°C to 70°C for C suffix and full range is -40°C to 125°C for I suffix. If not specified, full range is -40°C to 125°C .

input characteristics

PARAMETER		TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT
I _{IO}	Input offset current	V _{DD} = 5 V, V _{IC} = V _{DD} /2, V _O = V _{DD} /2, R _S = 50 Ω	25°C		1	60	pA
			70°C			100	
			125°C			1000	
I _{IB}	Input bias current		25°C		1	60	pA
			70°C			100	
			125°C			1000	
r _{i(d)}	Differential input resistance		25°C		1000		GΩ
C _{IC}	Common-mode input capacitance	f = 21 kHz	25°C		8		pF



TLV271, TLV272, TLV274
FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT
OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

electrical characteristics at specified free-air temperature, $V_{DD} = 2.7\text{ V}$, 5 V , and $\pm 5\text{ V}$ (unless otherwise noted)

output characteristics

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
V_{OH} High-level output voltage	$V_{IC} = V_{DD}/2$, $I_{OH} = -1\text{ mA}$	$V_{DD} = 2.7\text{ V}$	25°C	2.55	2.58	V
		Full range		2.48		
		$V_{DD} = 5\text{ V}$	25°C	4.9	4.93	
		Full range		4.85		
		$V_{DD} = \pm 5\text{ V}$	25°C	4.92	4.96	
		Full range		4.9		
	$V_{IC} = V_{DD}/2$, $I_{OH} = -5\text{ mA}$	$V_{DD} = 2.7\text{ V}$	25°C	1.9	2.1	
		Full range		1.5		
		$V_{DD} = 5\text{ V}$	25°C	4.6	4.68	
		Full range		4.5		
		$V_{DD} = \pm 5\text{ V}$	25°C	4.7	4.84	
		Full range		4.65		
V_{OL} Low-level output voltage	$V_{IC} = V_{DD}/2$, $I_{OL} = 1\text{ mA}$	$V_{DD} = 2.7\text{ V}$	25°C	0.1	0.15	V
		Full range		0.22		
		$V_{DD} = 5\text{ V}$	25°C	0.05	0.1	
		Full range		0.15		
		$V_{DD} = \pm 5\text{ V}$	25°C	-4.95	-4.92	
		Full range		-4.9		
	$V_{IC} = V_{DD}/2$, $I_{OL} = 5\text{ mA}$	$V_{DD} = 2.7\text{ V}$	25°C	0.5	0.7	
		Full range		1.1		
		$V_{DD} = 5\text{ V}$	25°C	0.28	0.4	
		Full range		0.5		
		$V_{DD} = \pm 5\text{ V}$	25°C	-4.84	-4.7	
		Full range		-4.65		
I_O Output current	$V_O = 0.5\text{ V}$ from rail, $V_{DD} = 2.7\text{ V}$	Positive rail	25°C	4		mA
		Negative rail	25°C	5		
	$V_O = 0.5\text{ V}$ from rail, $V_{DD} = 5\text{ V}$	Positive rail	25°C	7		
		Negative rail	25°C	8		
	$V_O = 0.5\text{ V}$ from rail, $V_{DD} = 10\text{ V}$	Positive rail	25°C	13		
		Negative rail	25°C	12		

† Full range is 0°C to 70°C for C suffix and full range is -40°C to 125°C for I suffix. If not specified, full range is -40°C to 125°C.

‡ Depending on package dissipation rating



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

TLV271, TLV272, TLV274
FAMILY OF 550-μA/Ch 3-MHz RAIL-TO-RAIL OUTPUT
OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

electrical characteristics at specified free-air temperature, $V_{DD} = 2.7\text{ V}$, 5 V , and $\pm 5\text{ V}$ (unless otherwise noted) (continued)

power supply

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
I_{DD} Supply current (per channel)	$V_O = V_{DD}/2$	$V_{DD} = 2.7\text{ V}$	25°C	470	560	μA
		$V_{DD} = 5\text{ V}$	25°C	550	660	
		$V_{DD} = 10\text{ V}$	25°C	625	800	
		Full range			1000	
PSRR Supply voltage rejection ratio ($\Delta V_{DD} / \Delta V_{IO}$)	$V_{DD} = 2.7\text{ V to } 16\text{ V}$, No load	$V_{IC} = V_{DD}/2$, 25°C	70	80		dB
		Full range	65			

† Full range is 0°C to 70°C for C suffix and full range is –40°C to 125°C for I suffix. If not specified, full range is –40°C to 125°C.

dynamic performance

PARAMETER	TEST CONDITIONS	$T_A^\dagger$	MIN	TYP	MAX	UNIT
UGBW Unity gain bandwidth	$R_L = 2\text{ k}\Omega$, $C_L = 10\text{ pF}$	$V_{DD} = 2.7\text{ V}$	25°C	2.4		MHz
		$V_{DD} = 5\text{ V to } 10\text{ V}$	25°C	3		
SR Slew rate at unity gain	$V_{O(PP)} = V_{DD}/2$, $C_L = 50\text{ pF}$, $R_L = 10\text{ k}\Omega$,	$V_{DD} = 2.7\text{ V}$	25°C	1.4	2.1	V/μs
			Full range	1		
		$V_{DD} = 5\text{ V}$	25°C	1.6	2.4	V/μs
			Full range	1.2		
		$V_{DD} = \pm 5\text{ V}$	25°C	1.8	2.6	V/μs
			Full range	1.3		
ϕ_m Phase margin	$R_L = 2\text{ k}\Omega$	$C_L = 10\text{ pF}$	25°C	65		°
Gain margin	$R_L = 2\text{ k}\Omega$	$C_L = 10\text{ pF}$	25°C	18		dB
t_s Settling time	$V_{DD} = 2.7\text{ V}$, $V_{(STEP)PP} = 1\text{ V}$, $A_V = -1$, $C_L = 10\text{ pF}$, $R_L = 2\text{ k}\Omega$	0.1%	25°C	2.9		μs
	$V_{DD} = 5\text{ V, } \pm 5\text{ V}$, $V_{(STEP)PP} = 1\text{ V}$, $A_V = -1$, $C_L = 47\text{ pF}$, $R_L = 2\text{ k}\Omega$	0.1%		2		

† Full range is 0°C to 70°C for C suffix and full range is –40°C to 125°C for I suffix. If not specified, full range is –40°C to 125°C.

noise/distortion performance

PARAMETER	TEST CONDITIONS	T_A	MIN	TYP	MAX	UNIT
THD + N Total harmonic distortion plus noise	$V_{DD} = 2.7\text{ V}$, $V_{O(PP)} = V_{DD}/2\text{ V}$, $R_L = 2\text{ k}\Omega$, $f = 10\text{ kHz}$	25°C	$A_V = 1$	0.02%		
			$A_V = 10$	0.05%		
			$A_V = 100$	0.18%		
	$V_{DD} = 5\text{ V, } \pm 5\text{ V}$, $V_{O(PP)} = V_{DD}/2\text{ V}$, $R_L = 2\text{ k}\Omega$, $f = 10\text{ K}$	25°C	$A_V = 1$	0.02%		
			$A_V = 10$	0.09%		
			$A_V = 100$	0.50%		
V_n Equivalent input noise voltage	$f = 1\text{ kHz}$	25°C		39		nV/√Hz
	$f = 10\text{ kHz}$			35		
I_n Equivalent input noise current	$f = 1\text{ kHz}$	25°C		0.6		fA/√Hz



TLV271, TLV272, TLV274
FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT
OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
CMRR	Common-mode rejection ratio	vs Frequency	1
	Input bias and offset current	vs Free-air temperature	2
V _{OL}	Low-level output voltage	vs Low-level output current	3, 5, 7
V _{OH}	High-level output voltage	vs High-level output current	4, 6, 8
V _{O(PP)}	Peak-to-peak output voltage	vs Frequency	9
I _{DD}	Supply current	vs Supply voltage	10
PSRR	Power supply rejection ratio	vs Frequency	11
A _{VD}	Differential voltage gain & phase	vs Frequency	12
	Gain-bandwidth product	vs Free-air temperature	13
SR	Slew rate	vs Supply voltage	14
		vs Free-air temperature	15
ϕ_m	Phase margin	vs Capacitive load	16
V _n	Equivalent input noise voltage	vs Frequency	17
	Voltage-follower large-signal pulse response		18, 19
	Voltage-follower small-signal pulse response		20
	Inverting large-signal response		21, 22
	Inverting small-signal response		23
	Crosstalk	vs Frequency	24



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

TYPICAL CHARACTERISTICS

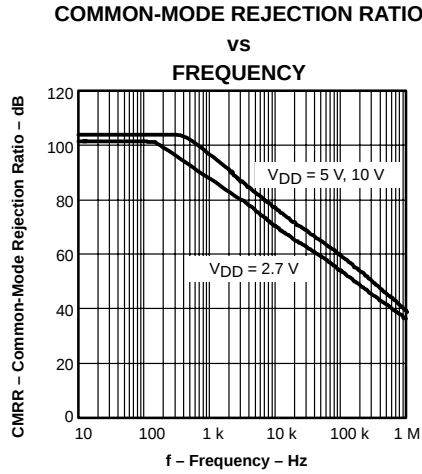


Figure 1

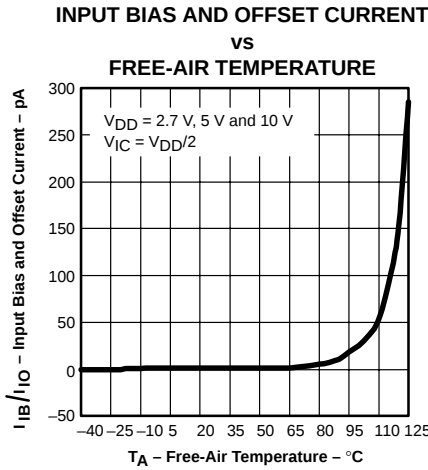


Figure 2

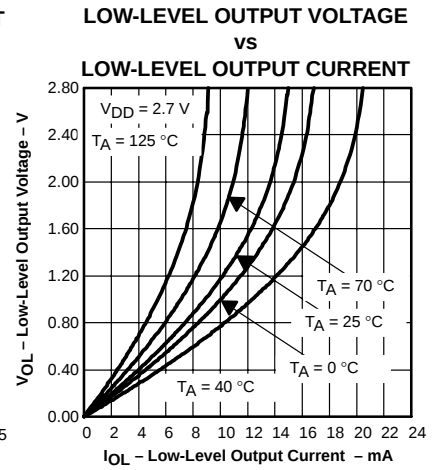


Figure 3

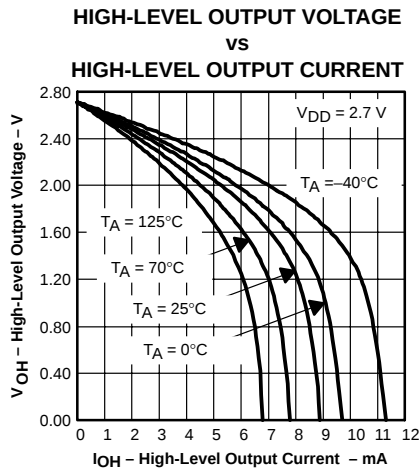


Figure 4

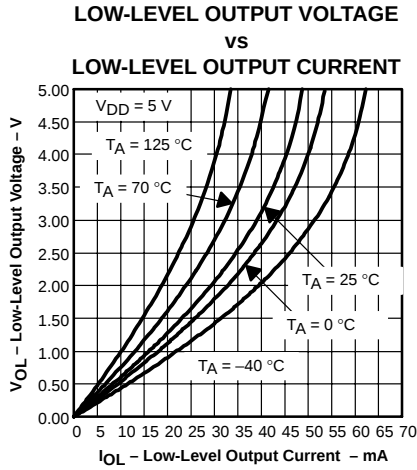


Figure 5

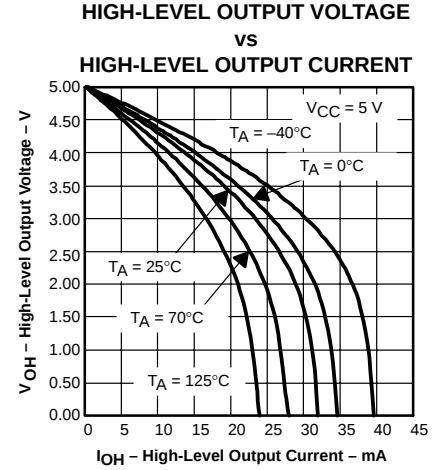


Figure 6

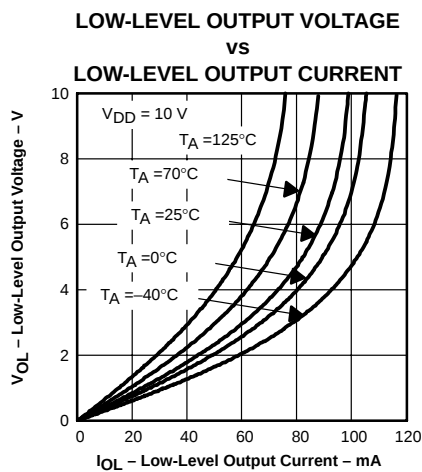


Figure 7

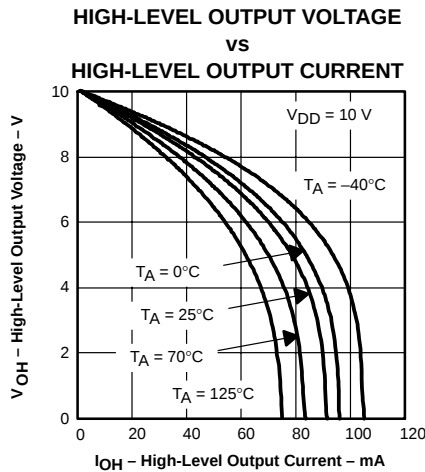


Figure 8

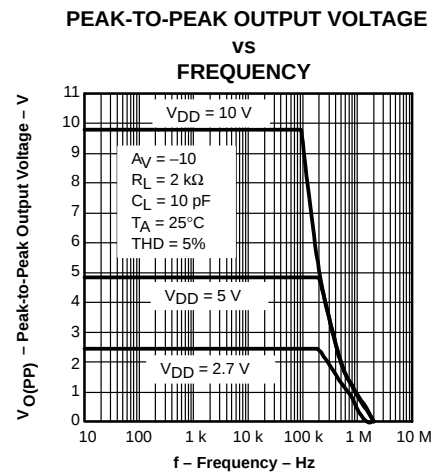


Figure 9

TLV271, TLV272, TLV274

FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

TYPICAL CHARACTERISTICS

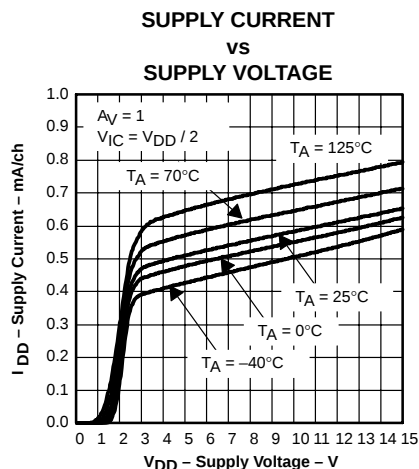


Figure 10

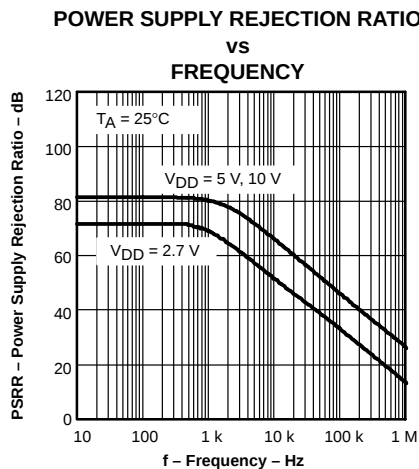


Figure 11

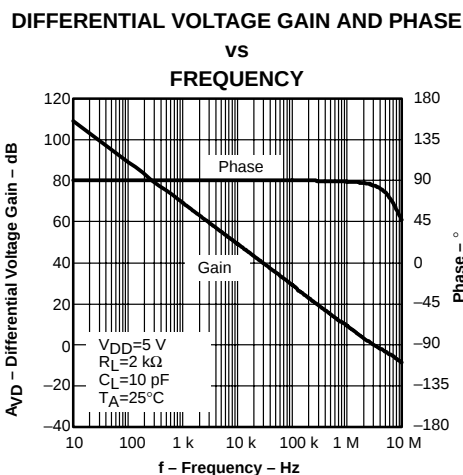


Figure 12

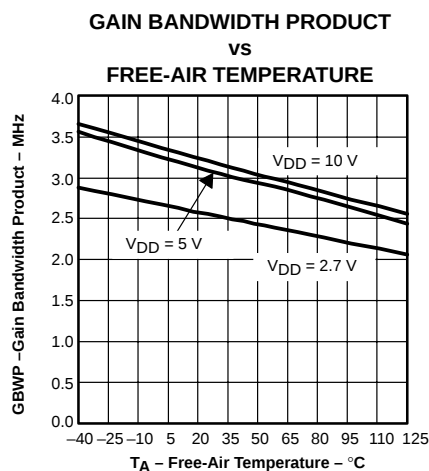


Figure 13

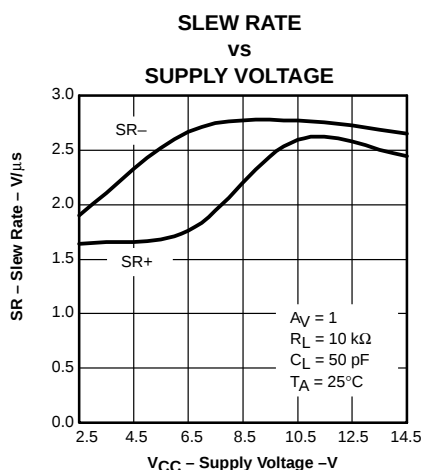


Figure 14

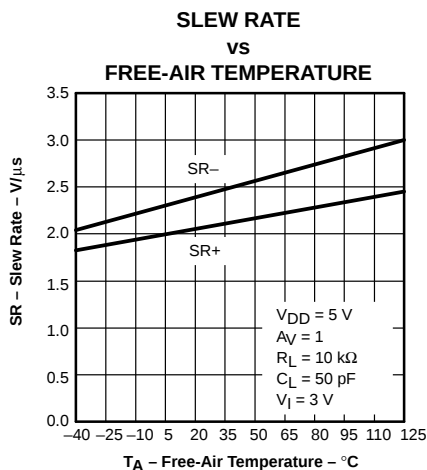


Figure 15

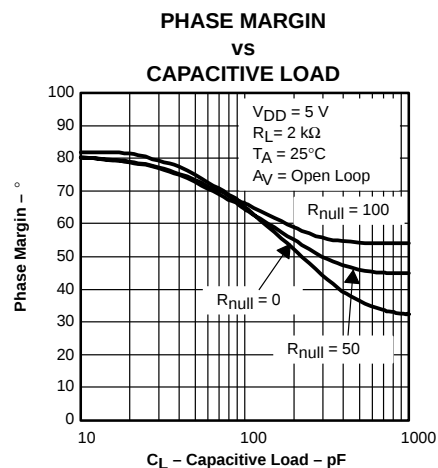


Figure 16



TYPICAL CHARACTERISTICS

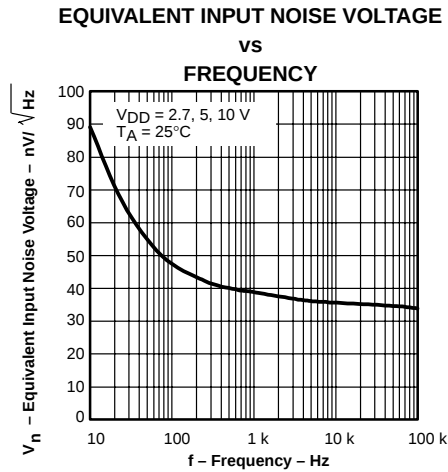


Figure 17

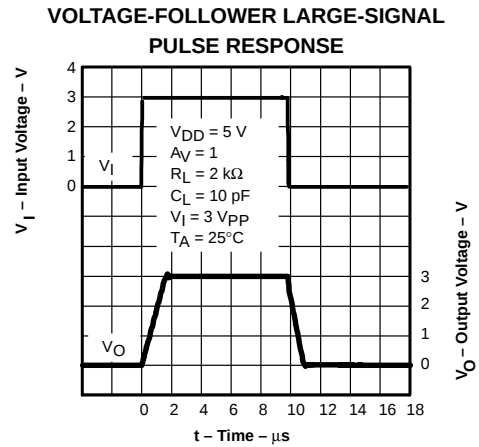


Figure 18

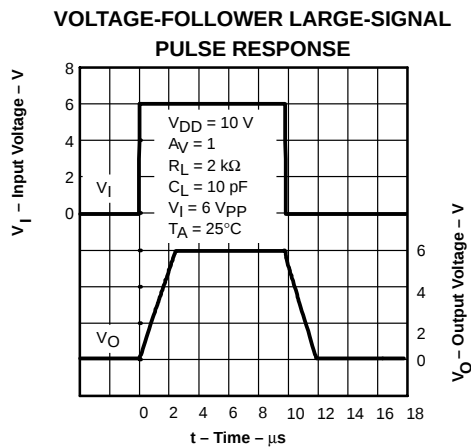


Figure 19

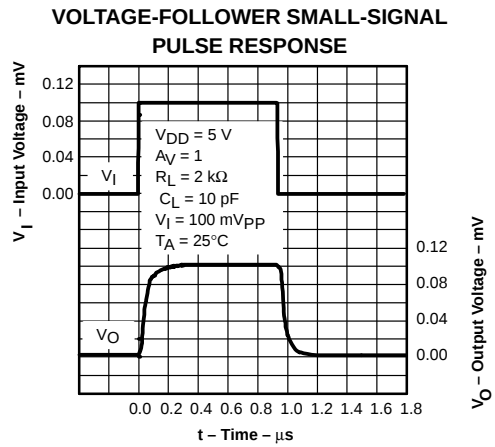


Figure 20

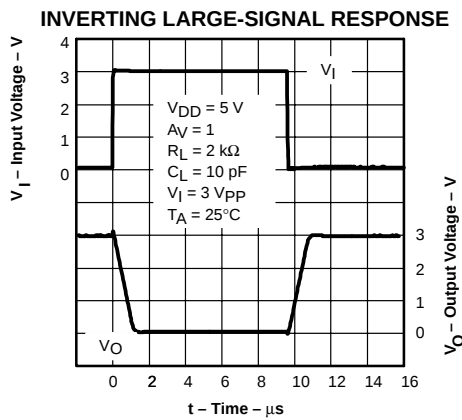


Figure 21

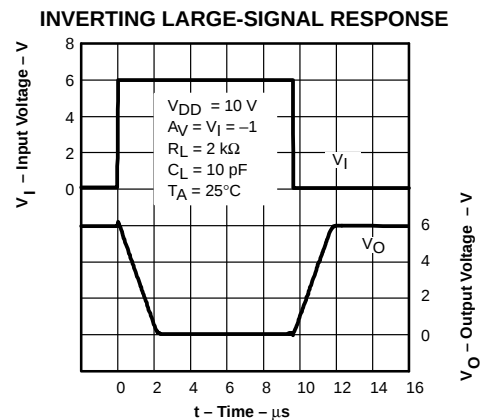


Figure 22

TLV271, TLV272, TLV274

FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

TYPICAL CHARACTERISTICS

INVERTING SMALL-SIGNAL RESPONSE

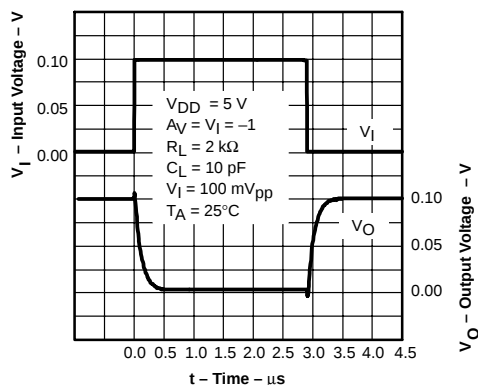


Figure 23

CROSSTALK
vs
FREQUENCY

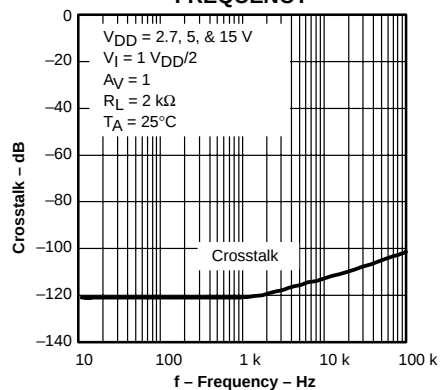


Figure 24

APPLICATION INFORMATION

driving a capacitive load

When the amplifier is configured in this manner, capacitive loading directly on the output decreases the device's phase margin leading to high frequency ringing or oscillations. Therefore, for capacitive loads of greater than 10 pF, it is recommended that a resistor be placed in series (R_{NULL}) with the output of the amplifier, as shown in Figure 25. A minimum value of 20 Ω should work well for most applications.

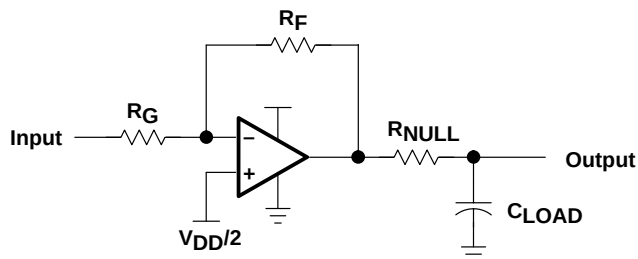


Figure 25. Driving a Capacitive Load

APPLICATION INFORMATION

offset voltage

The output offset voltage, (V_{OO}) is the sum of the input offset voltage (V_{IO}) and both input bias currents (I_{IB}) times the corresponding gains. The following schematic and formula can be used to calculate the output offset voltage:

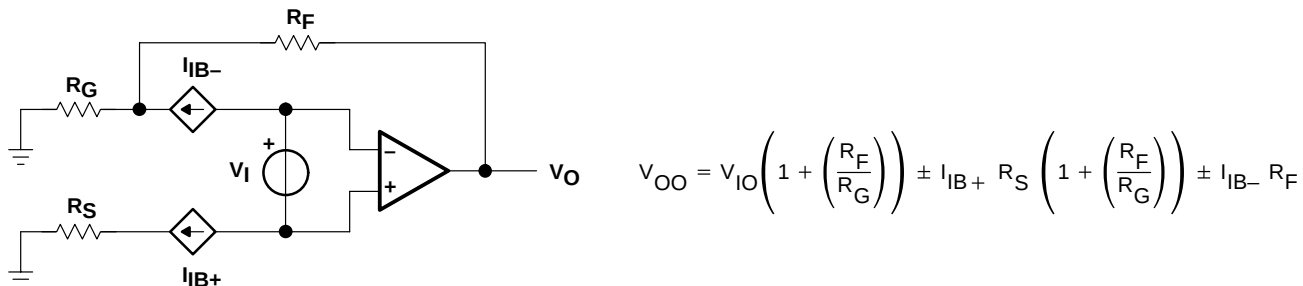


Figure 26. Output Offset Voltage Model

general configurations

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to accomplish this is to place an RC filter at the noninverting terminal of the amplifier (see Figure 27).

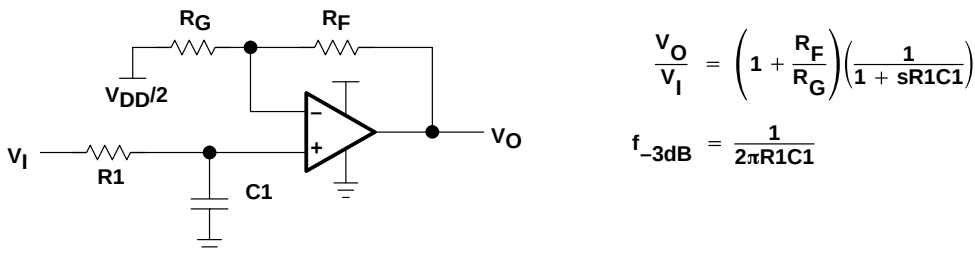


Figure 27. Single-Pole Low-Pass Filter

If even more attenuation is needed, a multiple pole filter is required. The Sallen-Key filter can be used for this task. For best results, the amplifier should have a bandwidth that is 8 to 10 times the filter frequency bandwidth. Failure to do this can result in phase shift of the amplifier.

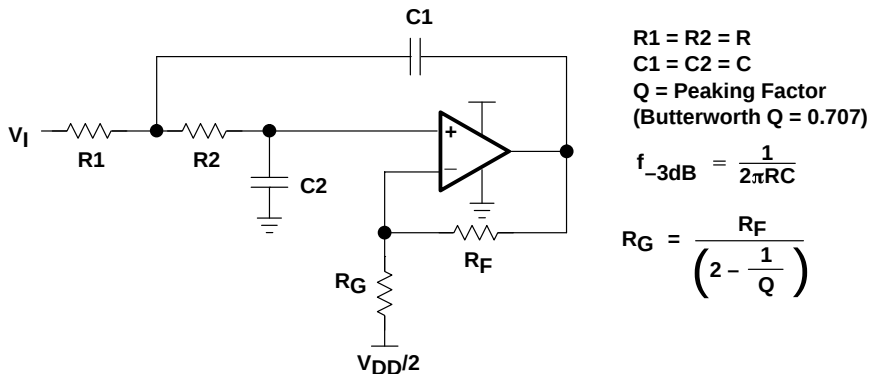


Figure 28. 2-Pole Low-Pass Sallen-Key Filter

TLV271, TLV272, TLV274

FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT

OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

APPLICATION INFORMATION

circuit layout considerations

To achieve the levels of high performance of the TLV27x, follow proper printed-circuit board design techniques. A general set of guidelines is given in the following.

- Ground planes—It is highly recommended that a ground plane be used on the board to provide all components with a low inductive ground connection. However, in the areas of the amplifier inputs and output, the ground plane can be removed to minimize the stray capacitance.
- Proper power supply decoupling—Use a 6.8- μ F tantalum capacitor in parallel with a 0.1- μ F ceramic capacitor on each supply terminal. It may be possible to share the tantalum among several amplifiers depending on the application, but a 0.1- μ F ceramic capacitor should always be used on the supply terminal of every amplifier. In addition, the 0.1- μ F capacitor should be placed as close as possible to the supply terminal. As this distance increases, the inductance in the connecting trace makes the capacitor less effective. The designer should strive for distances of less than 0.1 inches between the device power terminals and the ceramic capacitors.
- Sockets—Sockets can be used but are not recommended. The additional lead inductance in the socket pins will often lead to stability problems. Surface-mount packages soldered directly to the printed-circuit board is the best implementation.
- Short trace runs/compact part placements—Optimum high performance is achieved when stray series inductance has been minimized. To realize this, the circuit layout should be made as compact as possible, thereby minimizing the length of all trace runs. Particular attention should be paid to the inverting input of the amplifier. Its length should be kept as short as possible. This helps to minimize stray capacitance at the input of the amplifier.
- Surface-mount passive components—Using surface-mount passive components is recommended for high performance amplifier circuits for several reasons. First, because of the extremely low lead inductance of surface-mount components, the problem with stray series inductance is greatly reduced. Second, the small size of surface-mount components naturally leads to a more compact layout thereby minimizing both stray inductance and capacitance. If leaded components are used, it is recommended that the lead lengths be kept as short as possible.



APPLICATION INFORMATION

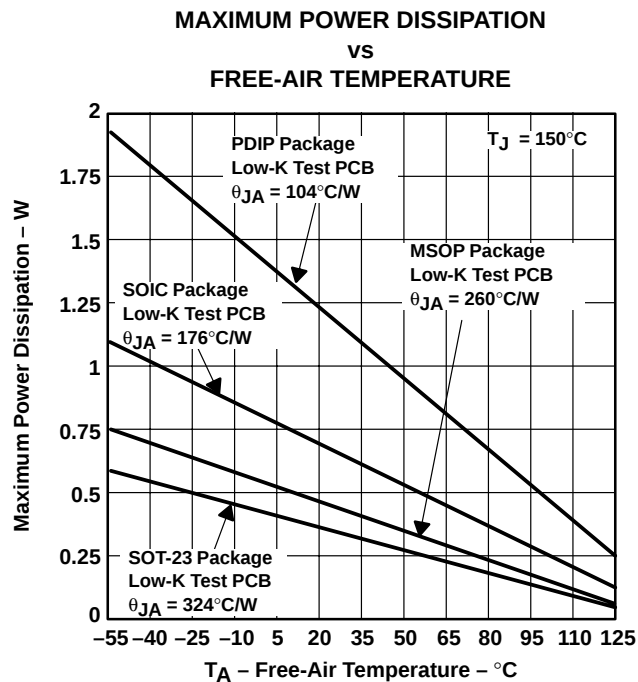
general power dissipation considerations

For a given θ_{JA} , the maximum power dissipation is shown in Figure 29 and is calculated by the following formula:

$$P_D = \left(\frac{T_{MAX} - T_A}{\theta_{JA}} \right)$$

Where:

- P_D = Maximum power dissipation of TLV27x IC (watts)
- T_{MAX} = Absolute maximum junction temperature (150°C)
- T_A = Free-ambient air temperature (°C)
- $\theta_{JA} = \theta_{JC} + \theta_{CA}$
- θ_{JC} = Thermal coefficient from junction to case
- θ_{CA} = Thermal coefficient from case to ambient air (°C/W)



NOTE A: Results are with no air flow and using JEDEC Standard Low-K test PCB.

Figure 29. Maximum Power Dissipation vs Free-Air Temperature

TLV271, TLV272, TLV274

FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

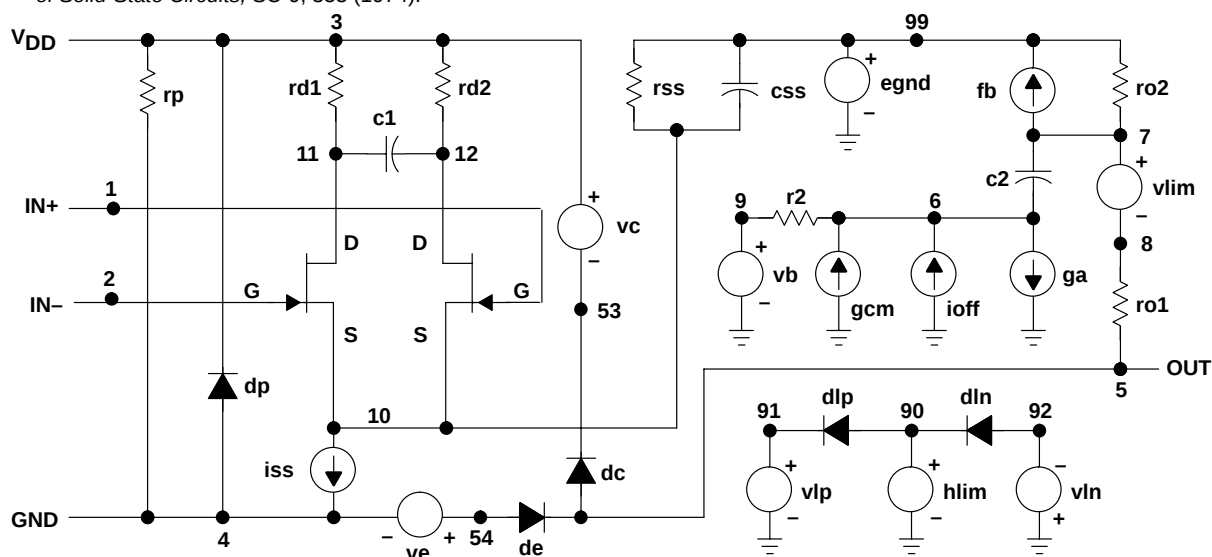
APPLICATION INFORMATION

macromodel information

Macromodel information provided was derived using Microsim *Parts*™ Release 9.1, the model generation software used with Microsim *PSpice*™. The Boyle macromodel (see Note 4) and subcircuit in Figure 30 are generated using TLV27x typical electrical and operating characteristics at $T_A = 25^\circ\text{C}$. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity-gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

NOTE 2: G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, "Macromodeling of Integrated Circuit Operational Amplifiers," *IEEE Journal of Solid-State Circuits*, SC-9, 353 (1974).



*DEVICE=amp_tlv27x_highVdd,OP AMP,NJF,INT
 * amp_tlv_27x_highVdd operational amplifier "macromodel"
 * subcircuit updated using Model Editor release 9.1 on 05/15/00
 * at 14:40 Model Editor is an OrCAD product.

* connections:

non-inverting input
 inverting input
 positive power supply
 negative power supply
 output

.subckt amp_tlv27x_highVdd

1 2 3 4 5
 c1 11 12 457.48E-15
 c2 6 7 5.0000E-12
 css 10 99 1.1431E-12
 dc 5 53 dy
 de 54 5 dy
 dlp 90 91 dx
 dln 92 90 dx
 dp 4 3 dx
 egnd 99 0 poly(2) (3,0) (4,0) 0 .5 .5
 fb 7 99 poly(5) vb vc ve vlp vln 0

176.02E6 -1E3 1E3 180E6
 -180E6

ga 6 0 11 12 16.272E-6
 gcm 0 6 10 99 6.8698E-9
 iss 10 4 dc 1.3371E-6
 hlim 90 0 vlim 1K
 j1 11 2 10 jx1
 j2 12 1 10 jx2
 r2 6 9 100.00E3
 rd1 3 11 61.456E3
 rd2 3 12 61.456E3
 ro1 8 5 10
 ro2 7 99 10
 rp 3 4 150.51E3
 rss 10 99 149.58E6
 vb 9 0 dc 0
 vc 3 53 dc .78905
 ve 54 4 dc .78905
 vlim 7 8 dc 0
 vlp 91 0 dc 14.200
 vln 0 92 dc 14.200
 .model dx D(Is=800.00E-18)
 .model dy D(Is=800.00E-18 Rs=1m Cjo=10p)
 .model jx1 NJF(Is=500.00E-15 Beta=198.03E-6 Vto=-1)
 .model jx2 NJF(Is=500.00E-15 Beta=198.03E-6 Vto=-1)
 .ends

Figure 30. Boyle Macromodel and Subcircuit

PSpice and Parts are trademarks of MicroSim Corporation.



TLV271, TLV272, TLV274
FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT
OPERATIONAL AMPLIFIERS

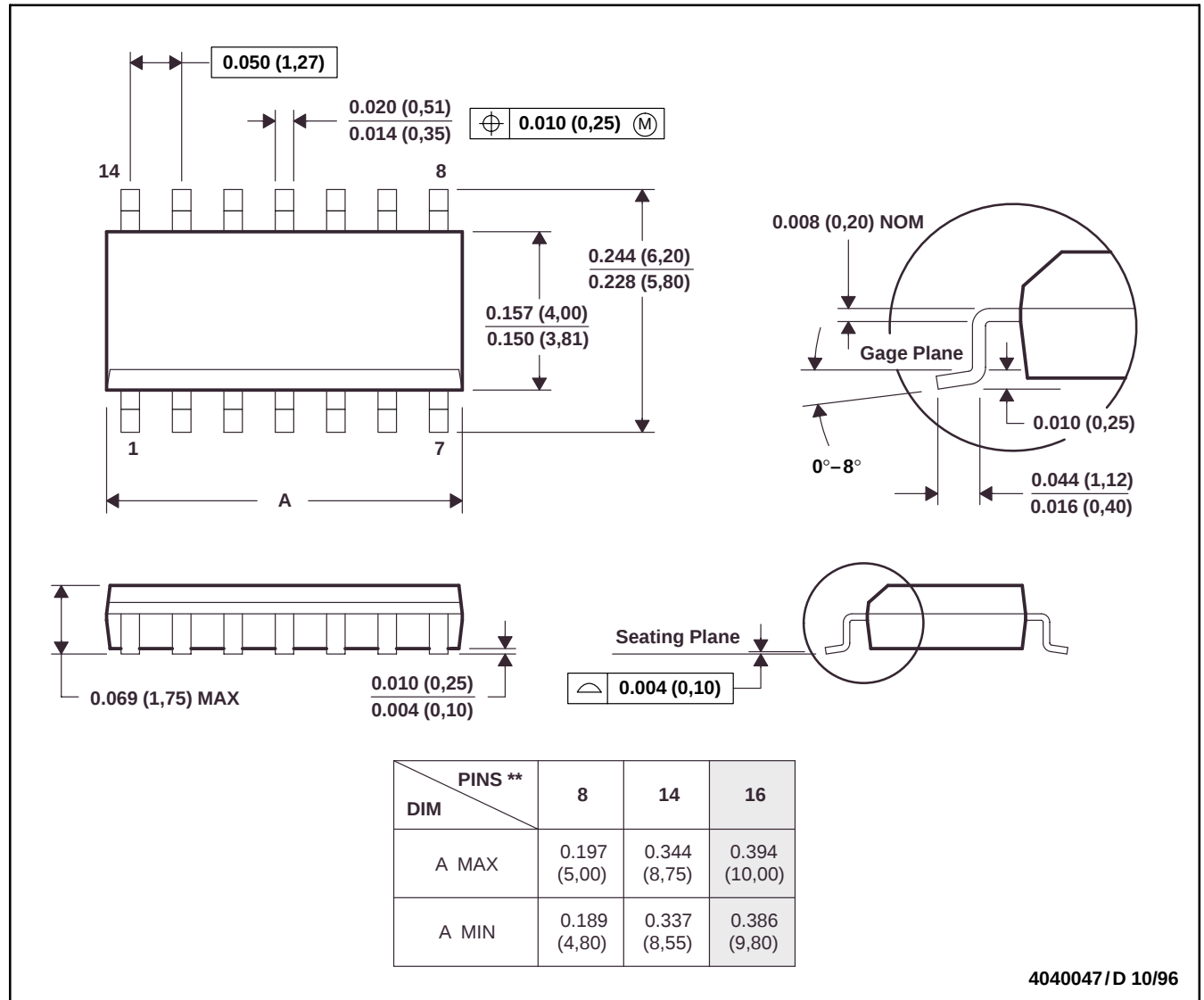
SLOS351C – MARCH 2001 – REVISED JULY 2002

MECHANICAL DATA

D (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

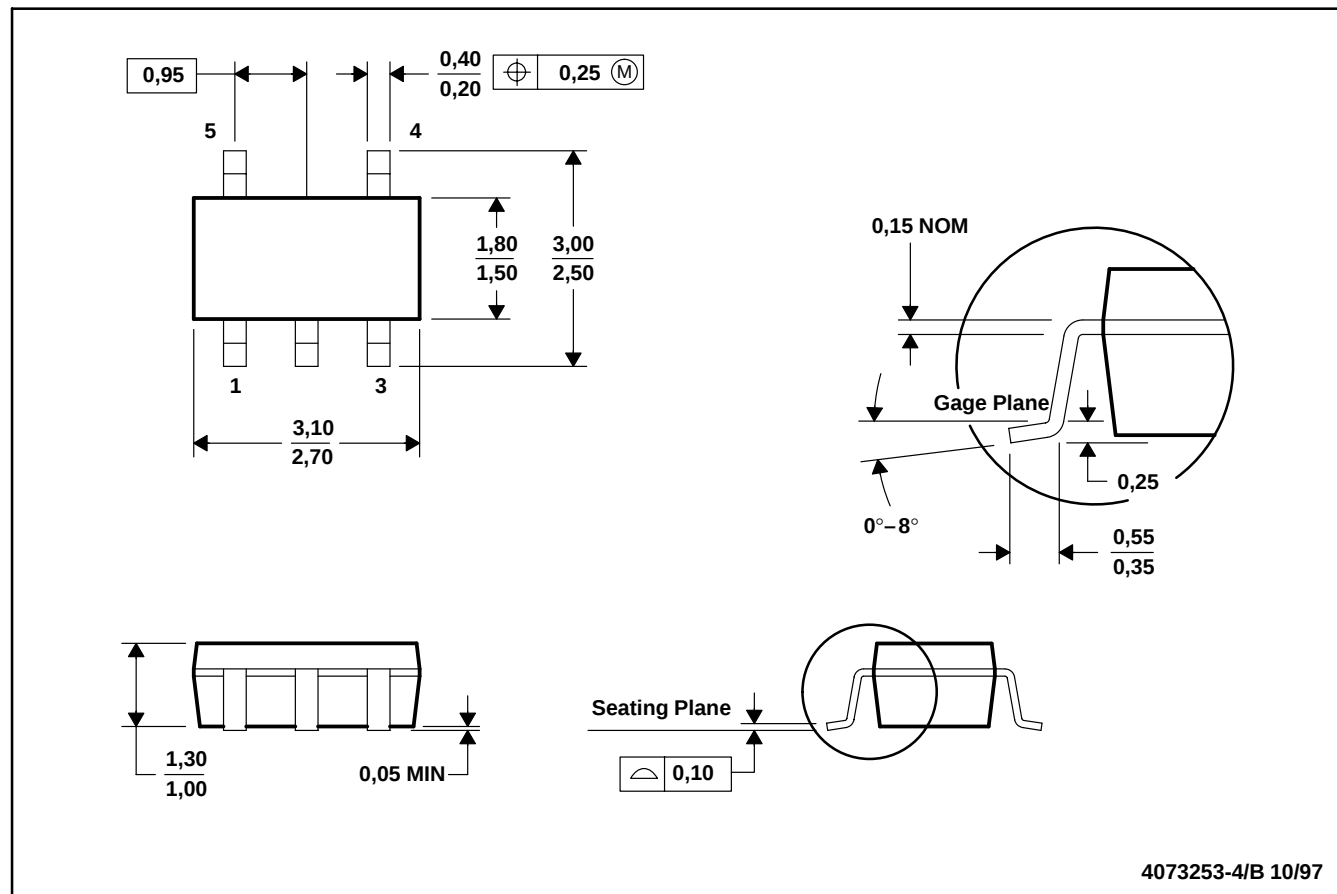
TLV271, TLV272, TLV274
FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT
OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

MECHANICAL INFORMATION

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions include mold flash or protrusion.

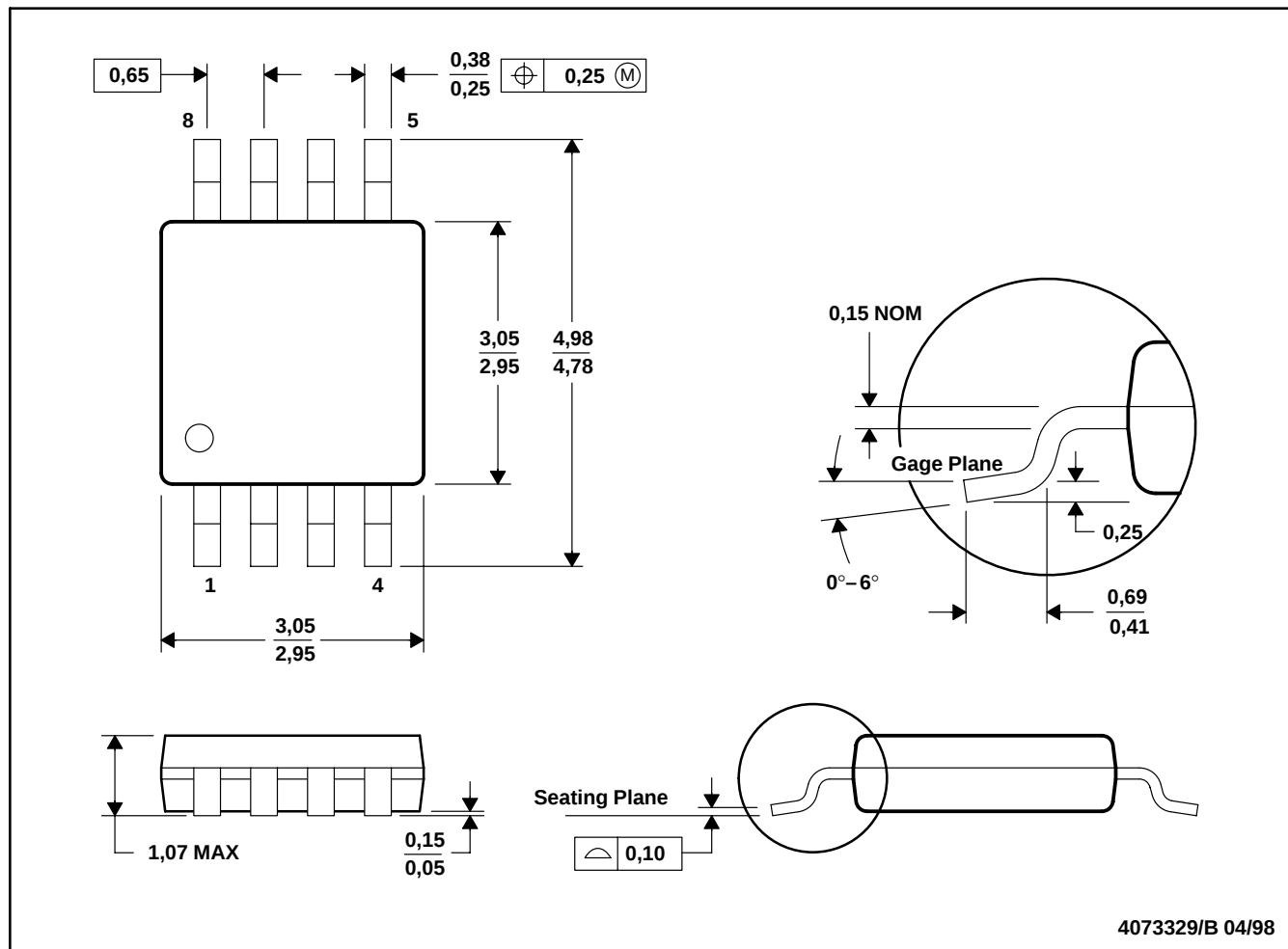
TLV271, TLV272, TLV274
FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT
OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

MECHANICAL INFORMATION

DGK (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion.
 D. Falls within JEDEC MO-187

TLV271, TLV272, TLV274

FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT

OPERATIONAL AMPLIFIERS

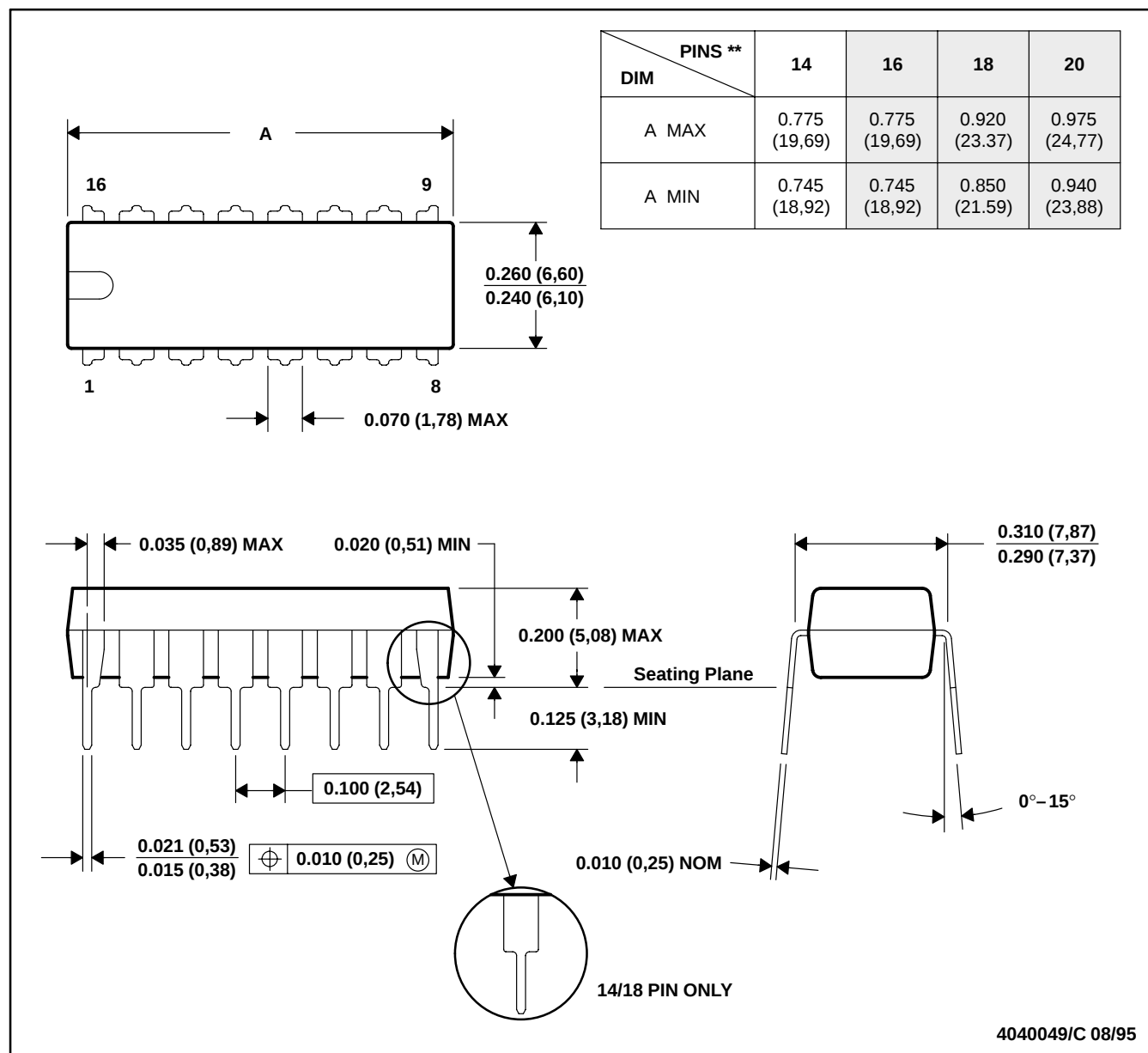
SLOS351C – MARCH 2001 – REVISED JULY 2002

MECHANICAL INFORMATION

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PIN SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 (20 pin package is shorter than MS-001.)

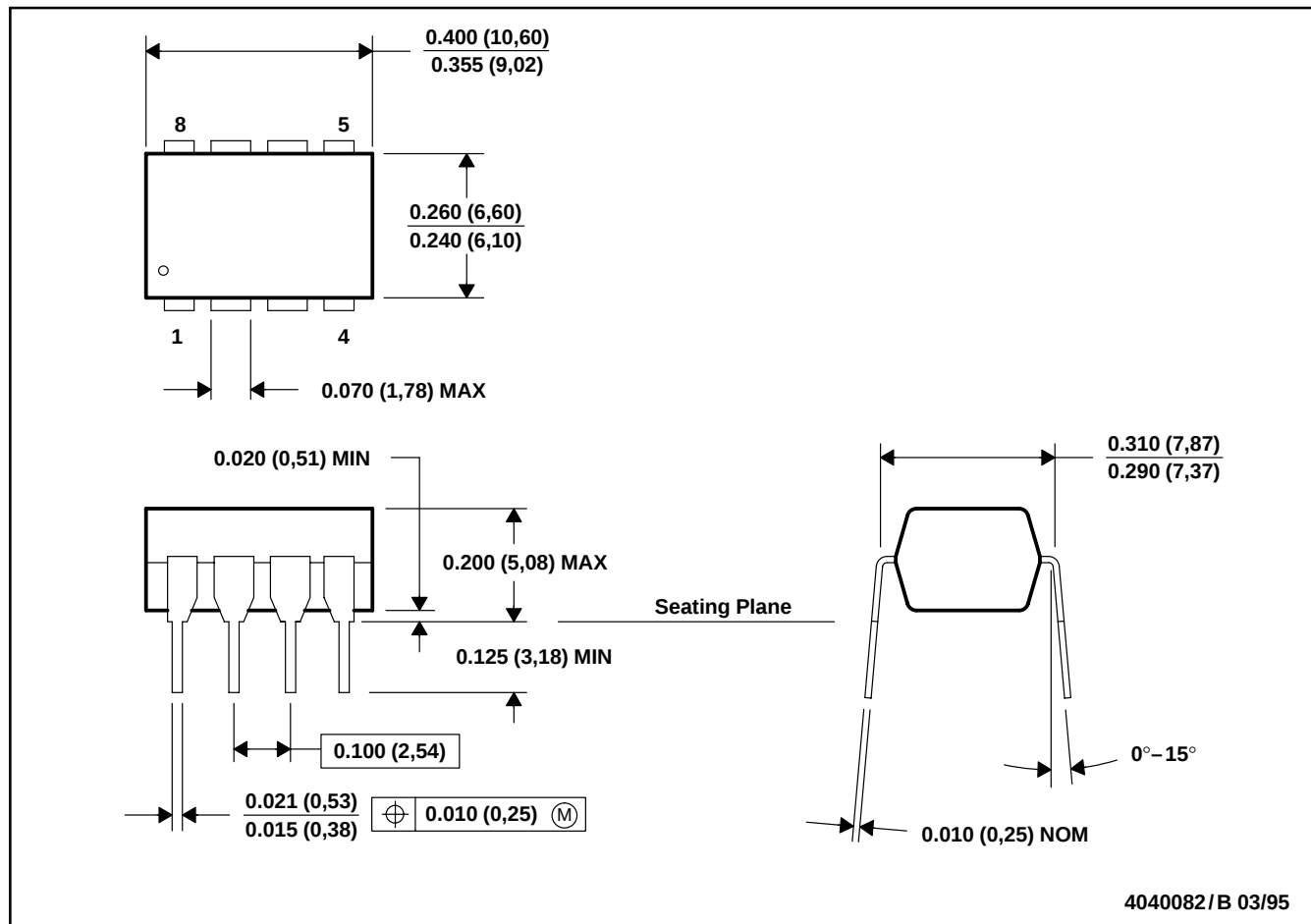
TLV271, TLV272, TLV274
FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT
OPERATIONAL AMPLIFIERS

SLOS351C – MARCH 2001 – REVISED JULY 2002

MECHANICAL INFORMATION

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

TLV271, TLV272, TLV274

FAMILY OF 550- μ A/Ch 3-MHz RAIL-TO-RAIL OUTPUT

OPERATIONAL AMPLIFIERS

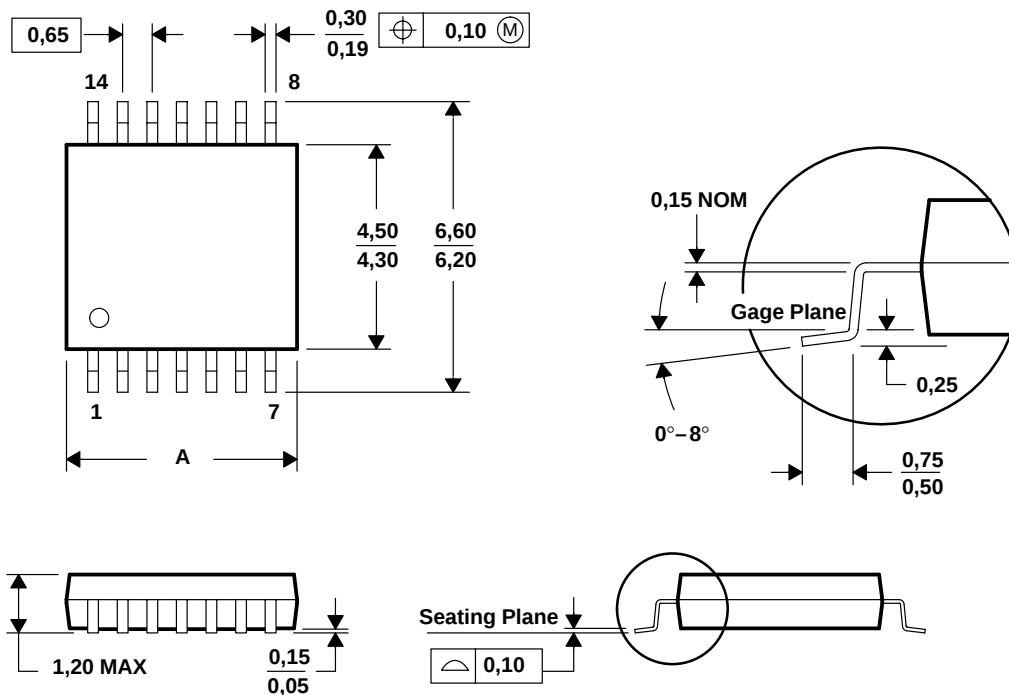
SLOS351C – MARCH 2001 – REVISED JULY 2002

MECHANICAL INFORMATION

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



PINS **	8	14	16	20	24	28
DIM						
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.